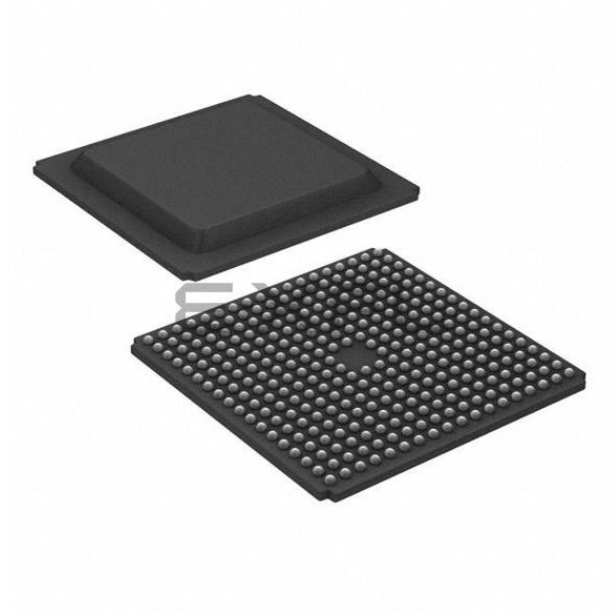
AMD Xilinx - XC3S400-4FG320C Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	896
Number of Logic Elements/Cells	8064
Total RAM Bits	294912
Number of I/O	221
Number of Gates	400000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	320-BGA
Supplier Device Package	320-FBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s400-4fg320c

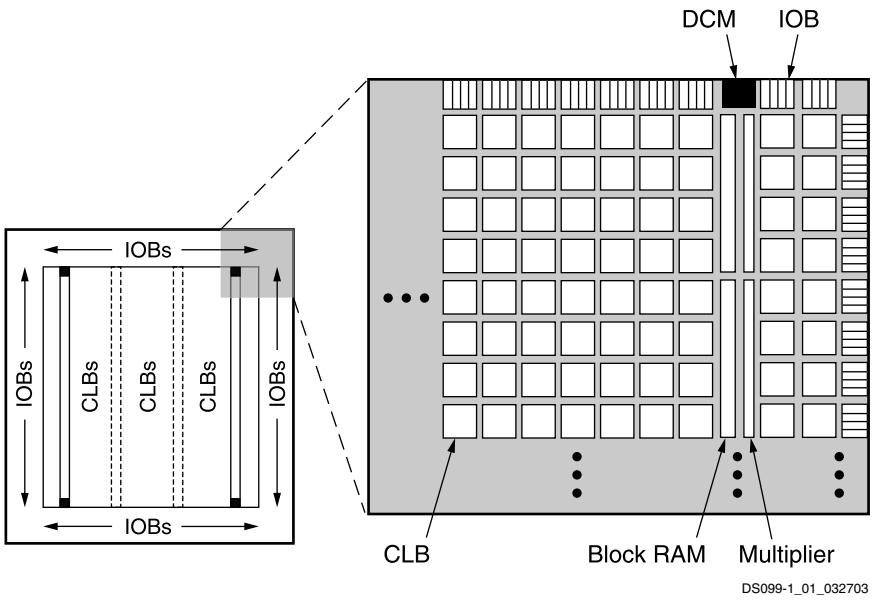
Architectural Overview

The Spartan-3 family architecture consists of five fundamental programmable functional elements:

- Configurable Logic Blocks (CLBs) contain RAM-based Look-Up Tables (LUTs) to implement logic and storage elements that can be used as flip-flops or latches. CLBs can be programmed to perform a wide variety of logical functions as well as to store data.
- Input/Output Blocks (IOBs) control the flow of data between the I/O pins and the internal logic of the device. Each IOB supports bidirectional data flow plus 3-state operation. Twenty-six different signal standards, including eight high-performance differential standards, are available as shown in Table 2. Double Data-Rate (DDR) registers are included. The Digitally Controlled Impedance (DCI) feature provides automatic on-chip terminations, simplifying board designs.
- Block RAM provides data storage in the form of 18-Kbit dual-port blocks.
- Multiplier blocks accept two 18-bit binary numbers as inputs and calculate the product.
- Digital Clock Manager (DCM) blocks provide self-calibrating, fully digital solutions for distributing, delaying, multiplying, dividing, and phase shifting clock signals.

These elements are organized as shown in Figure 1. A ring of IOBs surrounds a regular array of CLBs. The XC3S50 has a single column of block RAM embedded in the array. Those devices ranging from the XC3S200 to the XC3S2000 have two columns of block RAM. The XC3S4000 and XC3S5000 devices have four RAM columns. Each column is made up of several 18-Kbit RAM blocks; each block is associated with a dedicated multiplier. The DCMs are positioned at the ends of the outer block RAM columns.

The Spartan-3 family features a rich network of traces and switches that interconnect all five functional elements, transmitting signals among them. Each functional element has an associated switch matrix that permits multiple connections to the routing.



Notes:

1. The two additional block RAM columns of the XC3S4000 and XC3S5000 devices are shown with dashed lines. The XC3S50 has only the block RAM column on the far left.

Figure 1: **Spartan-3 Family Architecture**

Configuration

Spartan-3 FPGAs are programmed by loading configuration data into robust reprogrammable static CMOS configuration latches (CCLs) that collectively control all functional elements and routing resources. Before powering on the FPGA, configuration data is stored externally in a PROM or some other nonvolatile medium either on or off the board. After applying

IOBs

For additional information, refer to the chapter entitled “Using I/O Resources” in UG331: *Spartan-3 Generation FPGA User Guide*.

IOB Overview

The Input/Output Block (IOB) provides a programmable, bidirectional interface between an I/O pin and the FPGA’s internal logic.

A simplified diagram of the IOB’s internal structure appears in Figure 7. There are three main signal paths within the IOB: the output path, input path, and 3-state path. Each path has its own pair of storage elements that can act as either registers or latches. For more information, see the Storage Element Functions section. The three main signal paths are as follows:

- The input path carries data from the pad, which is bonded to a package pin, through an optional programmable delay element directly to the I line. There are alternate routes through a pair of storage elements to the IQ1 and IQ2 lines. The IOB outputs I, IQ1, and IQ2 all lead to the FPGA’s internal logic. The delay element can be set to ensure a hold time of zero.
- The output path, starting with the O1 and O2 lines, carries data from the FPGA’s internal logic through a multiplexer and then a three-state driver to the IOB pad. In addition to this direct path, the multiplexer provides the option to insert a pair of storage elements.
- The 3-state path determines when the output driver is high impedance. The T1 and T2 lines carry data from the FPGA’s internal logic through a multiplexer to the output driver. In addition to this direct path, the multiplexer provides the option to insert a pair of storage elements. When the T1 or T2 lines are asserted High, the output driver is high-impedance (floating, hi-Z). The output driver is active-Low enabled.
- All signal paths entering the IOB, including those associated with the storage elements, have an inverter option. Any inverter placed on these paths is automatically absorbed into the IOB.

Storage Element Functions

There are three pairs of storage elements in each IOB, one pair for each of the three paths. It is possible to configure each of these storage elements as an edge-triggered D-type flip-flop (FD) or a level-sensitive latch (LD).

The storage-element-pair on either the Output path or the Three-State path can be used together with a special multiplexer to produce Double-Data-Rate (DDR) transmission. This is accomplished by taking data synchronized to the clock signal’s rising edge and converting them to bits synchronized on both the rising and the falling edge. The combination of two registers and a multiplexer is referred to as a Double-Data-Rate D-type flip-flop (FDDR). See Double-Data-Rate Transmission, page 12 for more information.

The signal paths associated with the storage element are described in Table 5.

Table 5: **Storage Element Signal Description**

Storage Element Signal	Description	Function
D	Data input	Data at this input is stored on the active edge of CK enabled by CE. For latch operation when the input is enabled, data passes directly to the output Q.
Q	Data output	The data on this output reflects the state of the storage element. For operation as a latch in transparent mode, Q will mirror the data at D.
CK	Clock input	A signal’s active edge on this input with CE asserted, loads data into the storage element.
CE	Clock Enable input	When asserted, this input enables CK. If not connected, CE defaults to the asserted state.
SR	Set/Reset	Forces storage element into the state specified by the SRHIGH/SRLOW attributes. The SYNC/ASYNC attribute setting determines if the SR input is synchronized to the clock or not.
REV	Reverse	Used together with SR. Forces storage element into the state opposite from what SR does.

Table 9: **Differential I/O Standards**

Signal Standard (IOSTANDARD)	V_{CCO} (Volts)		V_{REF} for Inputs (Volts)
	For Outputs	For Inputs	
LDT_25 (ULVDS_25)	2.5	–	–
LVDS_25	2.5	–	–
BLVDS_25	2.5	–	–
LVDSEXT_25	2.5	–	–
LVPECL_25	2.5	–	–
RSDS_25	2.5	–	–
DIFF_HSTL_II_18	1.8	–	–
DIFF_SSTL2_II	2.5	–	–

Notes:

1. See Table 10 for a listing of the differential DCI standards.

The need to supply V_{REF} and V_{CCO} imposes constraints on which standards can be used in the same bank. See The Organization of IOBs into Banks section for additional guidelines concerning the use of the V_{CCO} and V_{REF} lines.

Digitally Controlled Impedance (DCI)

When the round-trip delay of an output signal—i.e., from output to input and back again—exceeds rise and fall times, it is common practice to add termination resistors to the line carrying the signal. These resistors effectively match the impedance of a device's I/O to the characteristic impedance of the transmission line, thereby preventing reflections that adversely affect signal integrity. However, with the high I/O counts supported by modern devices, adding resistors requires significantly more components and board area. Furthermore, for some packages—e.g., ball grid arrays—it may not always be possible to place resistors close to pins.

DCI answers these concerns by providing two kinds of on-chip terminations: Parallel terminations make use of an integrated resistor network. Series terminations result from controlling the impedance of output drivers. DCI actively adjusts both parallel and series terminations to accurately match the characteristic impedance of the transmission line. This adjustment process compensates for differences in I/O impedance that can result from normal variation in the ambient temperature, the supply voltage and the manufacturing process. When the output driver turns off, the series termination, by definition, approaches a very high impedance; in contrast, parallel termination resistors remain at the targeted values.

DCI is available only for certain I/O standards, as listed in Table 10. DCI is selected by applying the appropriate I/O standard extensions to symbols or components. There are five basic ways to configure terminations, as shown in Table 11. The DCI I/O standard determines which of these terminations is put into effect.

HSTL_I_DCI-, HSTL_III_DCI-, and SSTL2_I_DCI-type outputs do not require the VRN and VRP reference resistors. Likewise, LVDCI-type inputs do not require the VRN and VRP reference resistors. In a bank without any DCI I/O or a bank containing non-DCI I/O and purely HSTL_I_DCI- or HSTL_III_DCI-type outputs, or SSTL2_I_DCI-type outputs or LVDCI-type inputs, the associated VRN and VRP pins can be used as general-purpose I/O pins.

The HSLVDCI (High-Speed LVDCI) standard is intended for bidirectional use. The driver is identical to LVDCI, while the input is identical to HSTL. By using a V_{REF}-referenced input, HSLVDCI allows greater input sensitivity at the receiver than when using a single-ended LVCMOS-type receiver.

Coarse Phase Shift Outputs of the DLL Component

In addition to CLK0 for zero-phase alignment to the CLKIN signal, the DLL also provides the CLK90, CLK180 and CLK270 outputs for 90°, 180° and 270° phase-shifted signals, respectively. These signals are described in Table 16, page 33. Their relative timing in the Low Frequency Mode is shown in Figure 22, page 37. The CLK90, CLK180 and CLK270 outputs are not available when operating in the High Frequency mode. (See the description of the DLL_FREQUENCY_MODE attribute in Table 17, page 33.) For control in finer increments than 90°, see Phase Shifter (PS), page 39.

Basic Frequency Synthesis Outputs of the DLL Component

The DLL component provides basic options for frequency multiplication and division in addition to the more flexible synthesis capability of the DFS component, described in a later section. These operations result in output clock signals with frequencies that are either a fraction (for division) or a multiple (for multiplication) of the incoming clock frequency. The CLK2X output produces an in-phase signal that is twice the frequency of CLKIN. The CLK2X180 output also doubles the frequency, but is 180° out-of-phase with respect to CLKIN. The CLKDIV output generates a clock frequency that is a predetermined fraction of the CLKIN frequency. The CLKDV_DIVIDE attribute determines the factor used to divide the CLKIN frequency. The attribute can be set to various values as described in Table 17. The basic frequency synthesis outputs are described in Table 16. Their relative timing in the Low Frequency Mode is shown in Figure 22.

The CLK2X and CLK2X180 outputs are not available when operating in the High Frequency mode. See the description of the DLL_FREQUENCY_MODE attribute in Table 18.

Duty Cycle Correction of DLL Clock Outputs

The CLK2X[1], CLK2X180, and CLKDV[2] output signals ordinarily exhibit a 50% duty cycle—even if the incoming CLKIN signal has a different duty cycle. A 50% duty cycle means that the High and Low times of each clock cycle are equal. The DUTY_CYCLE_CORRECTION attribute determines whether or not duty cycle correction is applied to the CLK0, CLK90, CLK180 and CLK270 outputs. If DUTY_CYCLE_CORRECTION is set to TRUE, then the duty cycle of these four outputs is corrected to 50%. If DUTY_CYCLE_CORRECTION is set to FALSE, then these outputs exhibit the same duty cycle as the CLKIN signal. Figure 22 compares the characteristics of the DLL's output signals to those of the CLKIN signal.

1. The CLK2X output generates a 25% duty cycle clock at the same frequency as the CLKIN signal until the DLL has achieved lock.
2. The duty cycle of the CLKDV outputs may differ somewhat from 50% (i.e., the signal will be High for less than 50% of the period) when the CLKDV_DIVIDE attribute is set to a non-integer value *and* the DLL is operating in the High Frequency mode.

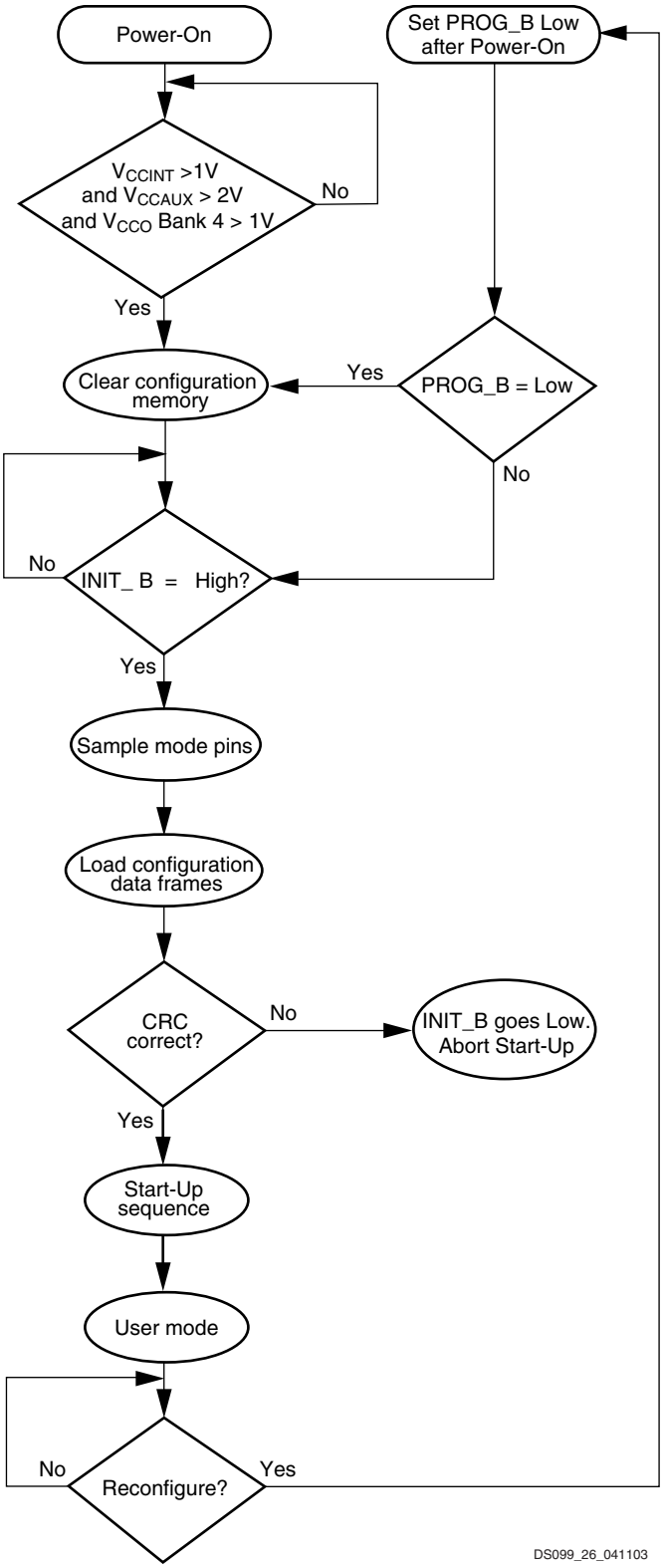


Figure 29: **Configuration Flow Diagram for the Serial and Parallel Modes**

Additional Configuration Details

Additional details about the Spartan-3 FPGA configuration architecture and command set are available in UG332: *Spartan-3 Generation Configuration User Guide* and in application note XAPP452: *Spartan-3 Advanced Configuration Architecture*.

Powering Spartan-3 FPGAs

Voltage Regulators

Various power supply manufacturers offer complete power solutions for Xilinx FPGAs, including some with integrated multi-rail regulators specifically designed for Spartan-3 FPGAs. The Xilinx Power Corner web page provides links to vendor solution guides as well as Xilinx power estimation and analysis tools.

Power Distribution System (PDS) Design and Bypass/Decoupling Capacitors

Good power distribution system (PDS) design is important for all FPGA designs, especially for high-performance applications. Proper design results in better overall performance, lower clock and DCM jitter, and a generally more robust system. Before designing the printed circuit board (PCB) for the FPGA design, review application note XAPP623: *Power Distribution System (PDS) Design: Using Bypass/Decoupling Capacitors*.

Power-On Behavior

Spartan-3 FPGAs have a built-in Power-On Reset (POR) circuit that monitors the three power rails required to successfully configure the FPGA. At power-up, the POR circuit holds the FPGA in a reset state until the V_{CCINT}, V_{CCAUX}, and V_{CCO} Bank 4 supplies reach their respective input threshold levels (see Table 29, page 59). After all three supplies reach their respective threshold, the POR reset is released and the FPGA begins its configuration process.

Because the three supply inputs must be valid to release the POR reset and can be supplied in any order, there are no specific voltage sequencing requirements. However, applying the FPGA's V_{CCAUX} supply before the V_{CCINT} supply uses the least I_{CCINT} current.

Once all three supplies are valid, the minimum current required to power-on the FPGA is equal to the worst-case quiescent current, as specified in Table 34, page 62. Spartan-3 FPGAs do not require Power-On Surge (POS) current to successfully configure.

Surplus I_{CCINT} if V_{CCINT} Applied before V_{CCAUX}

If the V_{CCINT} supply is applied before the V_{CCAUX} supply, the FPGA may draw a surplus I_{CCINT} current in addition to the I_{CCINT} quiescent current levels specified in Table 34. The momentary additional I_{CCINT} surplus current might be a few hundred milliamperes under nominal conditions, significantly less than the instantaneous current consumed by the bypass capacitors at power-on. However, the surplus current immediately disappears when the V_{CCAUX} supply is applied, and, in response, the FPGA's I_{CCINT} quiescent current demand drops to the levels specified in Table 34. The FPGA does not use nor does it require the surplus current to successfully power-on and configure. If applying V_{CCINT} before V_{CCAUX}, ensure that the regulator does not have a foldback feature that could inadvertently shut down in the presence of the surplus current.

Maximum Allowed V_{CCINT} Ramp Rate on Early Devices, if V_{VCCINT}Supply is Last in Sequence

All devices with a mask revision code 'E' or later do not have a V_{CCINT} ramp rate requirement. See Mask and Fab Revisions, page 58.

Early Spartan-3 FPGAs were produced at a 200 mm wafer production facility and are identified by a fabrication/process code of "FQ" on the device top marking, as shown in Package Marking, page 5. These "FQ" devices have a maximum V_{CCINT} ramp rate requirement if and only if V_{CCINT} is the last supply to ramp, after the V_{CCAUX} and V_{CCO} Bank 4 supplies. This maximum ramp rate appears as T_{CCINT} in Table 30, page 60.

Minimum Allowed V_{CCO} Ramp Rate on Early Devices

Devices shipped since 2006 essentially have no V_{CCO} ramp rate limits, shown in Table 30, page 60. Similarly, all devices with a mask revision code 'E' or later do not have a V_{CCO} ramp rate limit. See Mask and Fab Revisions, page 58.

Table 36: **DC Characteristics of User I/Os Using Single-Ended Standards**

Signal Standard (IOSTANDARD) and Current Drive Attribute (mA)		Test Conditions		Logic Level Characteristics	
		I_{OL} (mA)	I_{OH} (mA)	V_{OL} Max (V)	V_{OH} Min (V)
GTL		32	–	0.4	–
GTL_DCI		Note 3	Note 3		
GTLP		36	–	0.6	–
GTLP_DCI		Note 3	Note 3		
HSLVDCI_15		Note 3	Note 3	0.4	V_{CCO} – 0.4
HSLVDCI_18					
HSLVDCI_25					
HSLVDCI_33					
HSTL_I		8	–8	0.4	V_{CCO} – 0.4
HSTL_I_DCI		Note 3	Note 3		
HSTL_III		24	–8	0.4	V_{CCO} – 0.4
HSTL_III_DCI		Note 3	Note 3		
HSTL_I_18		8	–8	0.4	V_{CCO} – 0.4
HSTL_I_DCI_18		Note 3	Note 3		
HSTL_II_18		16	–16	0.4	V_{CCO} – 0.4
HSTL_II_DCI_18		Note 3	Note 3		
HSTL_III_18		24	–8	0.4	V_{CCO} – 0.4
HSTL_III_DCI_18		Note 3	Note 3		
LVCMOS12(4)	2	2	–2	0.4	V_{CCO} – 0.4
	4	4	–4		
	6	6	–6		
LVCMOS15(4)	2	2	–2	0.4	V_{CCO} – 0.4
	4	4	–4		
	6	6	–6		
	8	8	–8		
	12	12	–12		
LVDCI_15, LVDCI_DV2_15		Note 3	Note 3		
LVCMOS18(4)	2	2	–2	0.4	V_{CCO} – 0.4
	4	4	–4		
	6	6	–6		
	8	8	–8		
	12	12	–12		
	16	16	–16		
LVDCI_18, LVDCI_DV2_18		Note 3	Note 3		
LVCMOS25(4,5)	2	2	–2	0.4	V_{CCO} – 0.4
	4	4	–4		
	6	6	–6		
	8	8	–8		
	12	12	–12		
	16	16	–16		
	24	24	–24		
LVDCI_25, LVDCI_DV2_25		Note 3	Note 3		

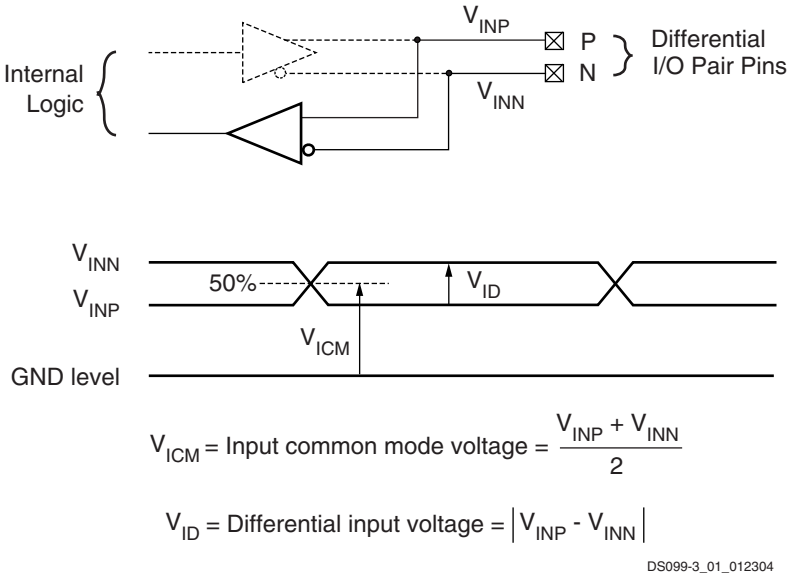


Figure 32: **Differential Input Voltages**

Table 37: **Recommended Operating Conditions for User I/Os Using Differential Signal Standards**

Signal Standard (IOSTANDARD)	V_{CCO}[1]			V_{ID}[3]			V_{ICM}		
	Min (V)	Nom (V)	Max (V)	Min (mV)	Nom (mV)	Max (mV)	Min (V)	Nom (V)	Max (V)
LDT_25 (ULVDS_25)	2.375	2.50	2.625	200	600	1000	0.44	0.60	0.78
LVDS_25, LVDS_25_DCI	2.375	2.50	2.625	100	350	600	0.30	1.25	2.20
BLVDS_25	2.375	2.50	2.625	-	350	-	-	1.25	-
LVDSEXT_25, LVDSEXT_25_DCI	2.375	2.50	2.625	100	540	1000	0.30	1.20	2.20
LVPECL_25	2.375	2.50	2.625	100	-	-	0.30	1.20	2.00
RSDS_25	2.375	2.50	2.625	100	200	-	-	1.20	-
DIFF_HSTL_II_18, DIFF_HSTL_II_18_DCI	1.70	1.80	1.90	200	-	-	0.80	-	1.00
DIFF_SSTL2_II, DIFF_SSTL2_II_DCI	2.375	2.50	2.625	300	-	-	1.05	-	1.45

Notes:

1. V_{CCO} only supplies differential output drivers, not input circuits.
2. V_{REF} inputs are not used for any of the differential I/O standards.
3. V_{ID} is a differential measurement.

Table 43: **Propagation Times for the IOB Input Path**

Symbol	Description	Conditions	Device	Speed Grade		Units
				-5	-4	
				Max	Max	
Propagation Times						
T_{IOPLI}	The time it takes for data to travel from the Input pin through the IFF latch to the I output with no input delay programmed	LVCMOS25(2), IOBDELAY = NONE	XC3S50	2.01	2.31	ns
			XC3S200	1.50	1.72	ns
			XC3S400	1.50	1.72	ns
			XC3S1000	2.01	2.31	ns
			XC3S1500	2.01	2.31	ns
			XC3S2000	2.01	2.31	ns
			XC3S4000	2.09	2.41	ns
			XC3S5000	2.18	2.51	ns
T_{IOPLID}	The time it takes for data to travel from the Input pin through the IFF latch to the I output with the input delay programmed	LVCMOS25(2), IOBDELAY = IFD	XC3S50	4.75	5.46	ns
			XC3S200	4.89	5.62	ns
			XC3S400	4.76	5.48	ns
			XC3S1000	5.38	6.18	ns
			XC3S1500	5.76	6.62	ns
			XC3S2000	7.04	8.09	ns
			XC3S4000	7.52	8.65	ns
			XC3S5000	7.69	8.84	ns

Notes:

1. The numbers in this table are tested using the methodology presented in Table 48 and are based on the operating conditions set forth in Table 32 and Table 35.
2. This propagation time requires adjustment whenever a signal standard other than LVCMOS25 is assigned to the data Input. When this is true, *add* the appropriate Input adjustment from Table 44.

Table 44: **Input Timing Adjustments for IOB**

Convert Input Time from LVCMOS25 to the Following Signal Standard (IOSTANDARD)	Add the Adjustment Below		Units
	Speed Grade		
	-5	-4	
Single-Ended Standards			
GTL, GTL_DCI	0.44	0.50	ns
GTLP, GTLP_DCI	0.36	0.42	ns
HSLVDCI_15	0.51	0.59	ns
HSLVDCI_18	0.29	0.33	ns
HSLVDCI_25	0.51	0.59	ns
HSLVDCI_33	0.51	0.59	ns
HSTL_I, HSTL_I_DCI	0.51	0.59	ns
HSTL_III, HSTL_III_DCI	0.37	0.42	ns
HSTL_I_18, HSTL_I_DCI_18	0.36	0.41	ns
HSTL_II_18, HSTL_II_DCI_18	0.39	0.45	ns
HSTL_III_18, HSTL_III_DCI_18	0.45	0.52	ns
LVCMOS12	0.63	0.72	ns

Table 48: **Test Methods for Timing Measurement at I/Os *(Cont'd)***

Signal Standard (IOSTANDARD)		Inputs			Outputs		Inputs and Outputs
		V_{REF} (V)	V_L (V)	V_H (V)	R_T (Ω)	V_T (V)	V_M (V)
HSTL_III_18		1.1	V_{REF} – 0.5	V_{REF} + 0.5	50	1.8	V_{REF}
HSTL_III_DCI_18							
LVCMOS12		-	0	1.2	1M	0	0.6
LVCMOS15		-	0	1.5	1M	0	0.75
LVDCI_15							
LVDCI_DV2_15							
HSLVDCI_15							
LVCMOS18		-	0	1.8	1M	0	0.9
LVDCI_18							
LVDCI_DV2_18							
HSLVDCI_18							
LVCMOS25		-	0	2.5	1M	0	1.25
LVDCI_25							
LVDCI_DV2_25							
HSLVDCI_25							
LVCMOS33		-	0	3.3	1M	0	1.65
LVDCI_33							
LVDCI_DV2_33							
HSLVDCI_33							
LVTTL		-	0	3.3	1M	0	1.4
PCI33_3	Rising	-	Note 3	Note 3	25	0	0.94
	Falling				25	3.3	2.03
SSTL18_I		0.9	V_{REF} – 0.5	V_{REF} + 0.5	50	0.9	V_{REF}
SSTL18_I_DCI							
SSTL18_II		0.9	V_{REF} – 0.5	V_{REF} + 0.5	50	0.9	V_{REF}
SSTL2_I		1.25	V_{REF} – 0.75	V_{REF} + 0.75	50	1.25	V_{REF}
SSTL2_I_DCI							
SSTL2_II		1.25	V_{REF} – 0.75	V_{REF} + 0.75	25	1.25	V_{REF}
SSTL2_II_DCI					50	1.25	
Differential							
LDT_25 (ULVDS_25)		-	V_{ICM} – 0.125	V_{ICM} + 0.125	60	0.6	V_{ICM}
LVDS_25		-	V_{ICM} – 0.125	V_{ICM} + 0.125	50	1.2	V_{ICM}
LVDS_25_DCI					N/A	N/A	
BLVDS_25		-	V_{ICM} – 0.125	V_{ICM} + 0.125	1M	0	V_{ICM}
LVDSEXT_25		-	V_{ICM} – 0.125	V_{ICM} + 0.125	50	1.2	V_{ICM}
LVDSEXT_25_DCI					N/A	N/A	
LVPECL_25		-	V_{ICM} – 0.3	V_{ICM} + 0.3	1M	0	V_{ICM}
RSDS_25		-	V_{ICM} – 0.1	V_{ICM} + 0.1	50	1.2	V_{ICM}
DIFF_HSTL_II_18		-	V_{ICM} – 0.5	V_{ICM} + 0.5	50	1.8	V_{ICM}
DIFF_HSTL_II_18_DCI							

Table 50: **Recommended Number of Simultaneously Switching Outputs per V_{CCO}/GND Pair *(Cont'd)***

Signal Standard (IOSTANDARD)			Package				
			VQ100	TQ144	PQ208	CP132	FT256, FG320, FG456, FG676, FG900, FG1156
LVDCI_15			6	6	6	6	14
LVDCI_DV2_15			6	6	6	6	14
HSLVDCI_15			6	6	6	6	14
LVCMOS18	Slow	2	19	13	13	29	64
		4	13	8	8	19	34
		6	8	8	8	9	22
		8	7	7	7	9	18
		12	5	5	5	5	13
		16	5	5	5	5	10
	Fast	2	13	13	13	19	36
		4	8	8	8	13	21
		6	8	8	8	8	13
		8	7	7	7	7	10
		12	5	5	5	5	9
		16	5	5	5	5	6
LVDCI_18			7	7	7	7	10
LVDCI_DV2_18			7	7	7	7	10
HSLVDCI_18			7	7	7	7	10
LVCMOS25	Slow	2	28	16	12	42	76
		4	13	10	10	19	46
		6	13	8	8	19	33
		8	7	7	7	9	24
		12	6	6	6	9	18
		16	6	6	6	6	11
		24	5	5	5	5	7
	Fast	2	17	12	12	26	42
		4	10	10	10	13	20
		6	8	8	8	13	15
		8	7	7	7	7	13
		12	6	6	6	6	11
		16	6	6	6	6	8
		24	5	5	5	5	5
LVDCI_25			7	7	7	7	11
LVDCI_DV2_25			7	7	7	7	11
HSLVDCI_25			7	7	7	7	11

Phase Shifter (PS)

Phase shifter operation is only supported if the DLL is in low-frequency mode, see Table 58. Fixed phase shift requires ISE software version 10.1.03 (or later).

Table 62: **Recommended Operating Conditions for the PS in Variable Phase Mode**

Symbol	Description	Frequency Mode/ F_{CLKIN} Range		Speed Grade				Units
				-5		-4		
				Min	Max	Min	Max	
Operating Frequency Ranges								
PSCLK_FREQ (F_{PSCLK})	Frequency for the PSCLK input	Low		1	167	1	167	MHz
Input Pulse Requirements								
PSCLK_PULSE	PSCLK pulse width as a percentage of the PSCLK period	Low	$F_{CLKIN} \leq 100$ MHz	40%	60%	40%	60%	-
			$F_{CLKIN} > 100$ MHz	45%	55%	45%	55%	-

Table 63: **Switching Characteristics for the PS in Variable or Fixed Phase Shift Mode**

Symbol	Description	Frequency Mode/ F_{CLKIN} Range	Speed Grade				Units
			-5		-4		
			Min	Max	Min	Max	
Phase Shifting Range							
FINE_SHIFT_RANGE	Phase shift range	Low	–	10.0	–	10.0	ns
Lock Time							
LOCK_DLL_PS	When using the PS in conjunction with the DLL: The time from deassertion at the DCM's Reset input to the rising transition at its LOCKED output. When the DCM is locked, the CLKIN and CLKFB signals are in phase.	18 MHz $\leq F_{CLKIN} \leq$ 30 MHz	–	3.28	–	3.28	ms
		30 MHz $< F_{CLKIN} \leq$ 40 MHz	–	2.56	–	2.56	ms
		40 MHz $< F_{CLKIN} \leq$ 50 MHz	–	1.60	–	1.60	ms
		50 MHz $< F_{CLKIN} \leq$ 60 MHz	–	1.00	–	1.00	ms
		60 MHz $< F_{CLKIN} \leq$ 165 MHz	–	0.88	–	0.88	ms
LOCK_DLL_PS_FX	When using the PS in conjunction with the DLL and DFS: The time from deassertion at the DCM's Reset input to the rising transition at its LOCKED output. When the DCM is locked, the CLKIN and CLKFB signals are in phase.	Low	–	10.40	–	10.40	ms

Notes:

1. The numbers in this table are based on the operating conditions set forth in Table 32 and Table 62.
2. The PS specifications in this table apply when the PS attribute CLKOUT_PHASE_SHIFT= VARIABLE or FIXED.

Table 70: **Spartan-3 FPGA Pin Definitions**

Pin Name	Direction	Description
I/O: General-purpose I/O pins		
I/O	User-defined as input, output, bidirectional, three-state output, open-drain output, open-source output	**User I/O:** Unrestricted single-ended user-I/O pin. Supports all I/O standards except the differential standards.
I/O_Lxxy_#	User-defined as input, output, bidirectional, three-state output, open-drain output, open-source output	**User I/O, Half of Differential Pair:** Unrestricted single-ended user-I/O pin or half of a differential pair. Supports all I/O standards including the differential standards.
DUAL: Dual-purpose configuration pins		
IO_Lxxy_#/DIN/D0, IO_Lxxy_#/D1, IO_Lxxy_#/D2, IO_Lxxy_#/D3, IO_Lxxy_#/D4, IO_Lxxy_#/D5, IO_Lxxy_#/D6, IO_Lxxy_#/D7	Input during configuration Possible bidirectional I/O after configuration if SelectMap port is retained Otherwise, user I/O after configuration	**Configuration Data Port:** In Parallel (SelectMAP) modes, D0-D7 are byte-wide configuration data pins. These pins become user I/Os after configuration unless the SelectMAP port is retained via the Persist bitstream option. In Serial modes, DIN (D0) serves as the single configuration data input. This pin becomes a user I/O after configuration unless retained by the Persist bitstream option.
IO_Lxxy_#/CS_B	Input during Parallel mode configuration Possible input after configuration if SelectMap port is retained Otherwise, user I/O after configuration	**Chip Select for Parallel Mode Configuration:** In Parallel (SelectMAP) modes, this is the active-Low Chip Select signal. This pin becomes a user I/O after configuration unless the SelectMAP port is retained via the Persist bitstream option.
IO_Lxxy_#/RDWR_B	Input during Parallel mode configuration Possible input after configuration if SelectMap port is retained Otherwise, user I/O after configuration	**Read/Write Control for Parallel Mode Configuration:** In Parallel (SelectMAP) modes, this is the active-Low Write Enable, active-High Read Enable signal. This pin becomes a user I/O after configuration unless the SelectMAP port is retained via the Persist bitstream option.
IO_Lxxy_#/ BUSY/DOUT	Output during configuration Possible output after configuration if SelectMap port is retained Otherwise, user I/O after configuration	**Configuration Data Rate Control for Parallel Mode, Serial Data Output for Serial Mode:** In Parallel (SelectMAP) modes, BUSY throttles the rate at which configuration data is loaded. This pin becomes a user I/O after configuration unless the SelectMAP port is retained via the Persist bitstream option. In Serial modes, DOUT provides preamble and configuration data to downstream devices in a multi-FPGA daisy-chain. This pin becomes a user I/O after configuration.
IO_Lxxy_#/INIT_B	Bidirectional (open-drain) during configuration User I/O after configuration	**Initializing Configuration Memory/Detected Configuration Error:** When Low, this pin indicates that configuration memory is being cleared. When held Low, this pin delays the start of configuration. After this pin is released or configuration memory is cleared, the pin goes High. During configuration, a Low on this output indicates that a configuration data error occurred. This pin always has an internal pull-up resistor to VCCO_4 or VCCO_BOTTOM during configuration, regardless of the HSWAP_EN pin. This pin becomes a user I/O after configuration.
DCI: Digitally Controlled Impedance reference resistor input pins		
IO_Lxxy_#/VRN_# or IO/VRN_#	Input when using DCI Otherwise, same as I/O	**DCI Reference Resistor for NMOS I/O Transistor (per bank):** If using DCI, a 1% precision impedance-matching resistor is connected between this pin and the VCCO supply for this bank. Otherwise, this pin is a user I/O.
IO_Lxxy_#/VRP_# or IO/VRP_#	Input when using DCI Otherwise, same as I/O	**DCI Reference Resistor for PMOS I/O Transistor (per bank):** If using DCI, a 1% precision impedance-matching resistor is connected between this pin and the ground supply. Otherwise, this pin is a user I/O.

Table 87: **VQ100 Package Pinout *(Cont'd)***

Bank	XC3S50 XC3S200 Pin Name	VQ100 Pin Number	Type
2	IO_L40N_2	P65	I/O
2	IO_L40P_2/VREF_2	P64	VREF
2	VCCO_2	P70	VCCO
3	IO	P55	I/O
3	IO	P59	I/O
3	IO_L01N_3/VRP_3	P54	DCI
3	IO_L01P_3/VRN_3	P53	DCI
3	IO_L24N_3	P61	I/O
3	IO_L24P_3	P60	I/O
3	IO_L40N_3/VREF_3	P63	VREF
3	IO_L40P_3	P62	I/O
3	VCCO_3	P57	VCCO
4	IO_L01N_4/VRP_4	P50	DCI
4	IO_L01P_4/VRN_4	P49	DCI
4	IO_L27N_4/DIN/D0	P48	DUAL
4	IO_L27P_4/D1	P47	DUAL
4	IO_L30N_4/D2	P44	DUAL
4	IO_L30P_4/D3	P43	DUAL
4	IO_L31N_4/INIT_B	P42	DUAL
4	IO_L31P_4/DOUT/BUSY	P40	DUAL
4	IO_L32N_4/GCLK1	P39	GCLK
4	IO_L32P_4/GCLK0	P38	GCLK
4	VCCO_4	P46	VCCO
5	IO_L01N_5/RDWR_B	P28	DUAL
5	IO_L01P_5/CS_B	P27	DUAL
5	IO_L28N_5/D6	P32	DUAL
5	IO_L28P_5/D7	P30	DUAL
5	IO_L31N_5/D4	P35	DUAL
5	IO_L31P_5/D5	P34	DUAL
5	IO_L32N_5/GCLK3	P37	GCLK
5	IO_L32P_5/GCLK2	P36	GCLK
5	VCCO_5	P31	VCCO
6	IO	P17	I/O
6	IO	P21	I/O
6	IO_L01N_6/VRP_6	P23	DCI
6	IO_L01P_6/VRN_6	P22	DCI
6	IO_L24N_6/VREF_6	P16	VREF
6	IO_L24P_6	P15	I/O
6	IO_L40N_6	P14	I/O

VQ100 Footprint

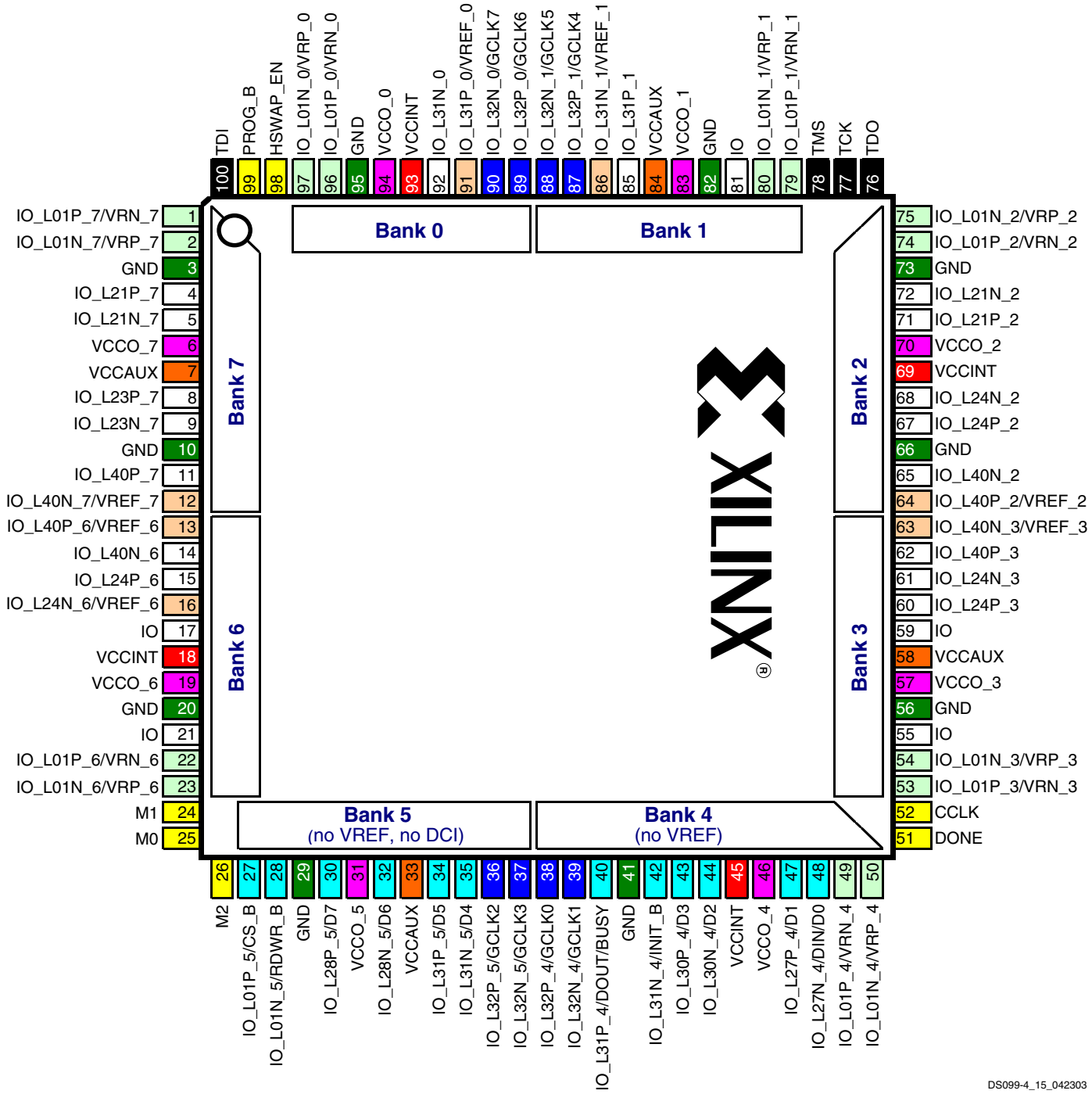


Figure 44: **VQ100 Package Footprint (Top View). Note pin 1 indicator in top-left corner and logo orientation.**

22	**I/O:** Unrestricted, general-purpose user I/O	12	**DUAL:** Configuration pin, then possible user I/O	7	**VREF:** User I/O or input voltage reference for bank
14	**DCI:** User I/O or reference resistor input for bank	8	**GCLK:** User I/O or global clock buffer input	8	**VCCO:** Output voltage supply for bank
7	**CONFIG:** Dedicated configuration pins	4	**JTAG:** Dedicated JTAG port pins	4	**VCCINT:** Internal core voltage supply (+1.2V)
0	**N.C.:** No unconnected pins in this package	10	**GND:** Ground	4	**VCCAUX:** Auxiliary voltage supply (+2.5V)

Table 89: **CP132 Package Pinout *(Cont'd)***

Bank	XC3S50 Pin Name	CP132 Ball	Type
2	IO_L24P_2	G13	I/O
2	IO_L40N_2	G14	I/O
2	IO_L40P_2/VREF_2	H12	VREF
3	IO_L01N_3/VRP_3	N13	DCI
3	IO_L01P_3/VRN_3	N14	DCI
3	IO_L20N_3	L12	I/O
3	IO_L20P_3	M14	I/O
3	IO_L22N_3	L14	I/O
3	IO_L22P_3	L13	I/O
3	IO_L23N_3	K13	I/O
3	IO_L23P_3/VREF_3	K12	VREF
3	IO_L24N_3	J12	I/O
3	IO_L24P_3	K14	I/O
3	IO_L40N_3/VREF_3	H14	VREF
3	IO_L40P_3	J13	I/O
4	IO/VREF_4	N12	VREF
4	IO_L01N_4/VRP_4	P12	DCI
4	IO_L01P_4/VRN_4	M11	DCI
4	IO_L27N_4/DIN/D0	M10	DUAL
4	IO_L27P_4/D1	N10	DUAL
4	IO_L30N_4/D2	N9	DUAL
4	IO_L30P_4/D3	P9	DUAL
4	IO_L31N_4/INIT_B	M8	DUAL
4	IO_L31P_4/DOUT/BUSY	N8	DUAL
4	IO_L32N_4/GCLK1	P8	GCLK
4	IO_L32P_4/GCLK0	M7	GCLK
5	IO_L01N_5/RDWR_B	P2	DUAL
5	IO_L01P_5/CS_B	N2	DUAL
5	IO_L27N_5/VREF_5	M4	VREF
5	IO_L27P_5	P3	I/O
5	IO_L28N_5/D6	P4	DUAL
5	IO_L28P_5/D7	N4	DUAL
5	IO_L31N_5/D4	M6	DUAL
5	IO_L31P_5/D5	P5	DUAL
5	IO_L32N_5/GCLK3	P7	GCLK
5	IO_L32P_5/GCLK2	P6	GCLK
6	IO_L01N_6/VRP_6	L3	DCI
6	IO_L01P_6/VRN_6	M1	DCI
6	IO_L20N_6	K3	I/O
6	IO_L20P_6	K2	I/O

Table 93: **PQ208 Package Pinout *(Cont'd)***

Bank	XC3S50 Pin Name	XC3S200, XC3S400 Pin Names	PQ208 Pin Number	Type
3	IO_L20P_3	IO_L20P_3	P114	I/O
3	IO_L21N_3	IO_L21N_3	P117	I/O
3	IO_L21P_3	IO_L21P_3	P116	I/O
3	IO_L22N_3	IO_L22N_3	P120	I/O
3	IO_L22P_3	IO_L22P_3	P119	I/O
3	IO_L23N_3	IO_L23N_3	P123	I/O
3	IO_L23P_3/VREF_3	IO_L23P_3/VREF_3	P122	VREF
3	IO_L24N_3	IO_L24N_3	P125	I/O
3	IO_L24P_3	IO_L24P_3	P124	I/O
3	N.C. (◆)	IO_L39N_3	P128	I/O
3	N.C. (◆)	IO_L39P_3	P126	I/O
3	IO_L40N_3/VREF_3	IO_L40N_3/VREF_3	P131	VREF
3	IO_L40P_3	IO_L40P_3	P130	I/O
3	VCCO_3	VCCO_3	P110	VCCO
3	VCCO_3	VCCO_3	P127	VCCO
4	IO	IO	P93	I/O
4	N.C. (◆)	IO	P97	I/O
4	IO/VREF_4	IO/VREF_4	P85	VREF
4	N.C. (◆)	IO/VREF_4	P96	VREF
4	IO/VREF_4	IO/VREF_4	P102	VREF
4	IO_L01N_4/VRP_4	IO_L01N_4/VRP_4	P101	DCI
4	IO_L01P_4/VRN_4	IO_L01P_4/VRN_4	P100	DCI
4	IO_L25N_4	IO_L25N_4	P95	I/O
4	IO_L25P_4	IO_L25P_4	P94	I/O
4	IO_L27N_4/DIN/D0	IO_L27N_4/DIN/D0	P92	DUAL
4	IO_L27P_4/D1	IO_L27P_4/D1	P90	DUAL
4	IO_L30N_4/D2	IO_L30N_4/D2	P87	DUAL
4	IO_L30P_4/D3	IO_L30P_4/D3	P86	DUAL
4	IO_L31N_4/INIT_B	IO_L31N_4/INIT_B	P83	DUAL
4	IO_L31P_4/DOUT/BUSY	IO_L31P_4/DOUT/BUSY	P81	DUAL
4	IO_L32N_4/GCLK1	IO_L32N_4/GCLK1	P80	GCLK
4	IO_L32P_4/GCLK0	IO_L32P_4/GCLK0	P79	GCLK
4	VCCO_4	VCCO_4	P84	VCCO
4	VCCO_4	VCCO_4	P98	VCCO
5	IO	IO	P63	I/O
5	IO	IO	P71	I/O
5	IO/VREF_5	IO/VREF_5	P78	VREF
5	IO_L01N_5/RDWR_B	IO_L01N_5/RDWR_B	P58	DUAL
5	IO_L01P_5/CS_B	IO_L01P_5/CS_B	P57	DUAL
5	IO_L10N_5/VRP_5	IO_L10N_5/VRP_5	P62	DCI

Table 103: **FG676 Package Pinout *(Cont'd)***

Bank	XC3S1000 Pin Name	XC3S1500 Pin Name	XC3S2000 Pin Name	XC3S4000 Pin Name	XC3S5000 Pin Name	FG676 Pin Number	Type
5	IO_L01P_5/CS_B	IO_L01P_5/CS_B	IO_L01P_5/CS_B	IO_L01P_5/CS_B	IO_L01P_5/CS_B	AB5	DUAL
5	IO_L04N_5	IO_L04N_5	IO_L04N_5	IO_L04N_5	IO_L04N_5	AE4	I/O
5	IO_L04P_5	IO_L04P_5	IO_L04P_5	IO_L04P_5	IO_L04P_5	AD4	I/O
5	IO_L05N_5	IO_L05N_5	IO_L05N_5	IO_L05N_5	IO_L05N_5	AB6	I/O
5	IO_L05P_5	IO_L05P_5	IO_L05P_5	IO_L05P_5	IO_L05P_5	AA6	I/O
5	IO_L06N_5	IO_L06N_5	IO_L06N_5	IO_L06N_5	IO_L06N_5	AE5	I/O
5	IO_L06P_5	IO_L06P_5	IO_L06P_5	IO_L06P_5	IO_L06P_5	AD5	I/O
5	IO_L07N_5	IO_L07N_5	IO_L07N_5	IO_L07N_5	IO_L07N_5	AD6	I/O
5	IO_L07P_5	IO_L07P_5	IO_L07P_5	IO_L07P_5	IO_L07P_5	AC6	I/O
5	IO_L08N_5	IO_L08N_5	IO_L08N_5	IO_L08N_5	IO_L08N_5	AF6	I/O
5	IO_L08P_5	IO_L08P_5	IO_L08P_5	IO_L08P_5	IO_L08P_5	AE6	I/O
5	IO_L09N_5	IO_L09N_5	IO_L09N_5	IO_L09N_5	IO_L09N_5	AC7	I/O
5	IO_L09P_5	IO_L09P_5	IO_L09P_5	IO_L09P_5	IO_L09P_5	AB7	I/O
5	IO_L10N_5/VRP_5	IO_L10N_5/VRP_5	IO_L10N_5/VRP_5	IO_L10N_5/VRP_5	IO_L10N_5/VRP_5	AF7	DCI
5	IO_L10P_5/VRN_5	IO_L10P_5/VRN_5	IO_L10P_5/VRN_5	IO_L10P_5/VRN_5	IO_L10P_5/VRN_5	AE7	DCI
5	N.C. (◆)	IO_L11N_5/VREF_5	IO_L11N_5/VREF_5	IO_L11N_5/VREF_5	IO_L11N_5/VREF_5	AB8	VREF
5	N.C. (◆)	IO_L11P_5	IO_L11P_5	IO_L11P_5	IO_L11P_5	AA8	I/O
5	N.C. (◆)	IO_L12N_5	IO_L12N_5	IO_L12N_5	IO_L12N_5	AD8	I/O
5	N.C. (◆)	IO_L12P_5	IO_L12P_5	IO_L12P_5	IO_L12P_5	AC8	I/O
5	IO_L15N_5	IO_L15N_5	IO_L15N_5	IO_L15N_5	IO_L15N_5	AF8	I/O
5	IO_L15P_5	IO_L15P_5	IO_L15P_5	IO_L15P_5	IO_L15P_5	AE8	I/O
5	IO_L16N_5	IO_L16N_5	IO_L16N_5	IO_L16N_5	IO_L16N_5	AA9	I/O
5	IO_L16P_5	IO_L16P_5	IO_L16P_5	IO_L16P_5	IO_L16P_5	Y9	I/O
5	N.C. (◆)	IO_L18N_5	IO_L18N_5	IO_L18N_5	IO_L18N_5	AE9	I/O
5	N.C. (◆)	IO_L18P_5	IO_L18P_5	IO_L18P_5	IO_L18P_5	AD9	I/O
5	IO_L19N_5	IO_L19N_5	IO_L19N_5	IO_L19N_5	IO_L19N_5	AA10	I/O
5	IO_L19P_5/VREF_5	IO_L19P_5/VREF_5	IO_L19P_5/VREF_5	IO_L19P_5/VREF_5	IO_L19P_5/VREF_5	Y10	VREF
5	IO_L22N_5	IO_L22N_5	IO_L22N_5	IO_L22N_5	IO_L22N_5	AC10	I/O
5	IO_L22P_5	IO_L22P_5	IO_L22P_5	IO_L22P_5	IO_L22P_5	AB10	I/O
5	N.C. (◆)	IO_L23N_5	IO_L23N_5	IO_L23N_5	IO_L23N_5	AF10	I/O
5	N.C. (◆)	IO_L23P_5	IO_L23P_5	IO_L23P_5	IO_L23P_5	AE10	I/O
5	IO_L24N_5	IO_L24N_5	IO_L24N_5	IO_L24N_5	IO_L24N_5	Y11	I/O
5	IO_L24P_5	IO_L24P_5	IO_L24P_5	IO_L24P_5	IO_L24P_5	W11	I/O
5	IO_L25N_5	IO_L25N_5	IO_L25N_5	IO_L25N_5	IO_L25N_5	AB11	I/O
5	IO_L25P_5	IO_L25P_5	IO_L25P_5	IO_L25P_5	IO_L25P_5	AA11	I/O
5	N.C. (◆)	IO_L26N_5	IO_L26N_5	IO_L26N_5	IO_L26N_5	AF11	I/O
5	N.C. (◆)	IO_L26P_5	IO_L26P_5	IO_L26P_5	IO_L26P_5	AE11	I/O
5	IO_L27N_5/VREF_5	IO_L27N_5/VREF_5	IO_L27N_5/VREF_5	IO_L27N_5/VREF_5	IO_L27N_5/VREF_5	Y12	VREF
5	IO_L27P_5	IO_L27P_5	IO_L27P_5	IO_L27P_5	IO_L27P_5	W12	I/O
5	IO_L28N_5/D6	IO_L28N_5/D6	IO_L28N_5/D6	IO_L28N_5/D6	IO_L28N_5/D6	AB12	DUAL
5	IO_L28P_5/D7	IO_L28P_5/D7	IO_L28P_5/D7	IO_L28P_5/D7	IO_L28P_5/D7	AA12	DUAL
5	IO_L29N_5	IO_L29N_5	IO_L29N_5	IO_L29N_5	IO_L29N_5	AF12	I/O

Table 107: **FG900 Package Pinout *(Cont'd)***

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
7	IO_L23N_7	IO_L23N_7	L3	I/O
7	IO_L23P_7	IO_L23P_7	L4	I/O
7	IO_L24N_7	IO_L24N_7	L1	I/O
7	IO_L24P_7	IO_L24P_7	L2	I/O
7	N.C. (◆)	IO_L25N_7	M6	I/O
7	N.C. (◆)	IO_L25P_7	M7	I/O
7	IO_L26N_7	IO_L26N_7	M3	I/O
7	IO_L26P_7	IO_L26P_7	M4	I/O
7	IO_L27N_7	IO_L27N_7	M1	I/O
7	IO_L27P_7/VREF_7	IO_L27P_7/VREF_7	M2	VREF
7	IO_L28N_7	IO_L28N_7	N10	I/O
7	IO_L28P_7	IO_L28P_7	M10	I/O
7	IO_L29N_7	IO_L29N_7	N8	I/O
7	IO_L29P_7	IO_L29P_7	N9	I/O
7	IO_L31N_7	IO_L31N_7	N1	I/O
7	IO_L31P_7	IO_L31P_7	N2	I/O
7	IO_L32N_7	IO_L32N_7	P9	I/O
7	IO_L32P_7	IO_L32P_7	P10	I/O
7	IO_L33N_7	IO_L33N_7	P6	I/O
7	IO_L33P_7	IO_L33P_7	P7	I/O
7	IO_L34N_7	IO_L34N_7	P2	I/O
7	IO_L34P_7	IO_L34P_7	P3	I/O
7	IO_L35N_7	IO_L35N_7	R9	I/O
7	IO_L35P_7	IO_L35P_7	R10	I/O
7	IO_L37N_7	IO_L37N_7	R7	I/O
7	IO_L37P_7/VREF_7	IO_L37P_7/VREF_7	R8	VREF
7	IO_L38N_7	IO_L38N_7	R5	I/O
7	IO_L38P_7	IO_L38P_7	R6	I/O
7	IO_L39N_7	IO_L39N_7	R3	I/O
7	IO_L39P_7	IO_L39P_7	R4	I/O
7	IO_L40N_7/VREF_7	IO_L40N_7/VREF_7	R1	VREF
7	IO_L40P_7	IO_L40P_7	R2	I/O
7	N.C. (◆)	IO_L46N_7	M8	I/O
7	N.C. (◆)	IO_L46P_7	M9	I/O
7	N.C. (◆)	IO_L49N_7	N6	I/O
7	N.C. (◆)	IO_L49P_7	M5	I/O
7	N.C. (◆)	IO_L50N_7	N4	I/O
7	N.C. (◆)	IO_L50P_7	N5	I/O
7	VCCO_7	VCCO_7	E3	VCCO
7	VCCO_7	VCCO_7	J3	VCCO

Table 110: **FG1156 Package Pinout *(Cont'd)***

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
4	VCCO_4	VCCO_4	AC19	VCCO
4	VCCO_4	VCCO_4	AC20	VCCO
4	VCCO_4	VCCO_4	AC21	VCCO
4	VCCO_4	VCCO_4	AC22	VCCO
4	VCCO_4	VCCO_4	AG20	VCCO
4	VCCO_4	VCCO_4	AG24	VCCO
4	VCCO_4	VCCO_4	AH27	VCCO
4	VCCO_4	VCCO_4	AJ22	VCCO
4	VCCO_4	VCCO_4	AL19	VCCO
4	VCCO_4	VCCO_4	AL24	VCCO
4	VCCO_4	VCCO_4	AM27	VCCO
4	VCCO_4	VCCO_4	AM31	VCCO
4	VCCO_4	VCCO_4	AN22	VCCO
5	IO	IO	AD11	I/O
5	N.C. (◆)	IO	AD12	I/O
5	IO	IO	AD14	I/O
5	IO	IO	AD15	I/O
5	IO	IO	AD16	I/O
5	IO	IO	AD17	I/O
5	IO	IO	AE14	I/O
5	IO	IO	AE16	I/O
5	N.C. (◆)	IO	AF9	I/O
5	IO	IO	AG9	I/O
5	IO	IO	AG12	I/O
5	IO	IO	AJ6	I/O
5	IO	IO	AJ17	I/O
5	IO	IO	AK10	I/O
5	IO	IO	AK14	I/O
5	IO	IO	AM12	I/O
5	IO	IO	AN9	I/O
5	IO/VREF_5	IO/VREF_5	AJ8	VREF
5	IO/VREF_5	IO/VREF_5	AL5	VREF
5	IO/VREF_5	IO/VREF_5	AP17	VREF
5	IO_L01N_5/RDWR_B	IO_L01N_5/RDWR_B	AP3	DUAL
5	IO_L01P_5/CS_B	IO_L01P_5/CS_B	AN3	DUAL
5	IO_L02N_5	IO_L02N_5	AP4	I/O
5	IO_L02P_5	IO_L02P_5	AN4	I/O
5	IO_L03N_5	IO_L03N_5	AN5	I/O
5	IO_L03P_5	IO_L03P_5	AM5	I/O
5	IO_L04N_5	IO_L04N_5	AM6	I/O